

**APPENDIX A – MARKED-UP VERSION OF AMENDED CLAIMS**

- [[c1]]1. A windowframe capacitor, comprising:
- a housing having a bottom surface[ and], a top surface,[ wherein]and an aperture [is formed ]in a central portion thereof extending from the top surface to the bottom surface; and
- capacitive material disposed within the housing to create a desired amount of capacitance;
- wherein the bottom surface is provided with electrical connections adapted to be connected to a substrate.
- [[c2]]2. The windowframe capacitor of Claim 1, wherein the aperture is rectangular.
- [[c3]]3. The windowframe capacitor of Claim 1, wherein the capacitive material comprises a layer of an electrically conductive material and a layer of a dielectric material.
- [[c4]]4. The windowframe capacitor of Claim 3, wherein the housing is made from a plastic material.
- [[c5]]5. The windowframe capacitor of Claim 1, wherein said electrical connections provided on the bottom surface comprise a ball grid array.
- [[c6]]6. The windowframe capacitor of Claim 1, wherein the capacitive material and the housing comprise co-fired ceramic.
- [[c7]]7. The windowframe capacitor of Claim 1, wherein the aperture is configured to fit over a semiconductor die, and wherein said electrical connections are configured for connection to a package substrate on which the semiconductor die is mounted.
- [[c8]]8. A semiconductor package assembly, comprising:

a semiconductor die mounted on a portion of a top surface of a package substrate;  
and

a windowframe capacitor having an aperture formed therein, and mounted on the  
top surface of the package substrate surrounding the semiconductor die.

- [[c9]]9. The semiconductor package assembly of Claim 8, further comprising an  
electronic component mounted on a top surface of the windowframe capacitor.
- [[c10]]10. The semiconductor package assembly of Claim 8, further comprising a second  
windowframe capacitor mounted on a top surface of the first windowframe  
capacitor.
- [[c11]]11. The semiconductor package assembly of Claim 8, wherein the aperture is  
rectangular.
- [[c12]]12. The semiconductor package assembly of Claim 8, wherein the windowframe  
capacitor comprises a housing.
- [[c13]]13. The semiconductor package assembly of Claim 12, wherein the windowframe  
capacitor comprises a capacitive material disposed within the housing.
- [[c14]]14. The semiconductor package assembly of Claim 13, wherein the capacitive  
material comprises a layer of an electrically conductive material and a layer of a  
dielectric material.
- [[c15]]15. The semiconductor package assembly of Claim 14, wherein the housing is made  
of a plastic material.
- [[c16]]16. The semiconductor package assembly of Claim 13, wherein the capacitive  
material and the housing comprise a co-fired ceramic.
- [[c17]]17. The semiconductor package assembly of Claim 8, wherein the windowframe  
capacitor is mounted on the package substrate via a ball grid array.